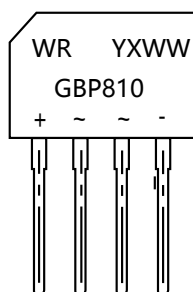


Ultrasoft Recovery Bridge



PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

Features

- Glass Passivated Chip Junction
- Reverse Voltage - 1000 V
- Forward Current - 8.0 A
- High Surge Current Capability
- Designed For Surface Mount Application

Benefits

- Case: D3K
- Terminals: Solderable Per MIL-STD-750

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

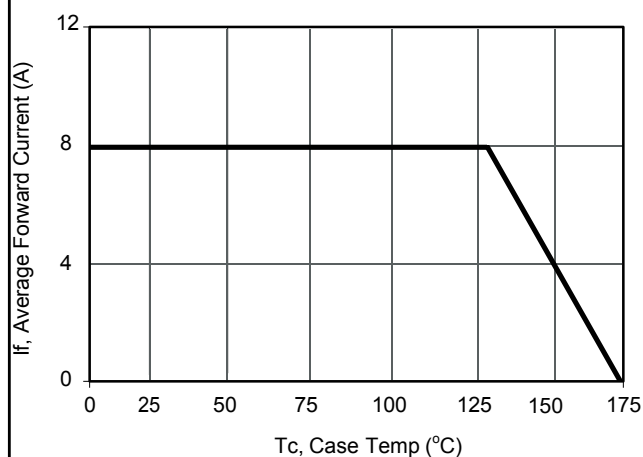
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	WRGBP810	Units
Maximum Repetitive Peak Reverse Voltage	VRRM	1000	V
Maximum RMS voltage	VRMS	700	V
Maximum DC Blocking Voltage	VDC	1000	V
Average Rectified Output Current	I _o	8.0	A
Reverse Recovery Time. IF=0.5A, IR=1A, IRR=0.25A	T _{rr}	10	us
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	180	A
I ² t rating for fusing (1ms< t < 10ms)	I ² t	93	A ² S
Maximum Forward Voltage at 4.0 A	V _F	1.0	V
Maximum DC Reverse Current @TA=25 °C at Rated DC Blocking Voltage @TA=125 °C	I _R	5 100	μA
Typical Junction Capacitance (Note1)	C _j	50	pF
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +175	°C

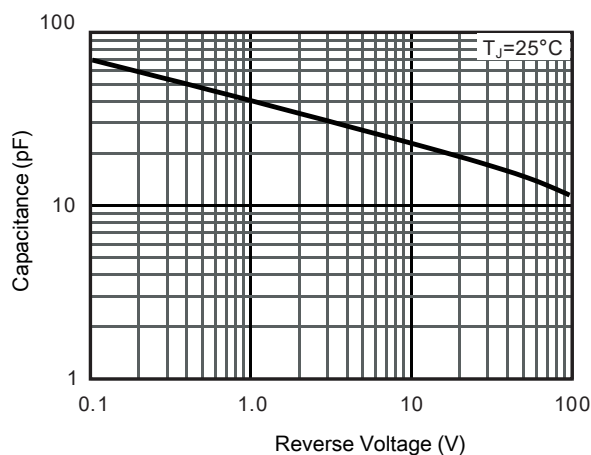
Note: 1. Measured at 1MHz and applied reverse voltage of 4 VDC.

2. Mounted on glass epoxy PC board with 4 × 1.5" × 1.5" (3.81 × 3.81 cm) copper pad.

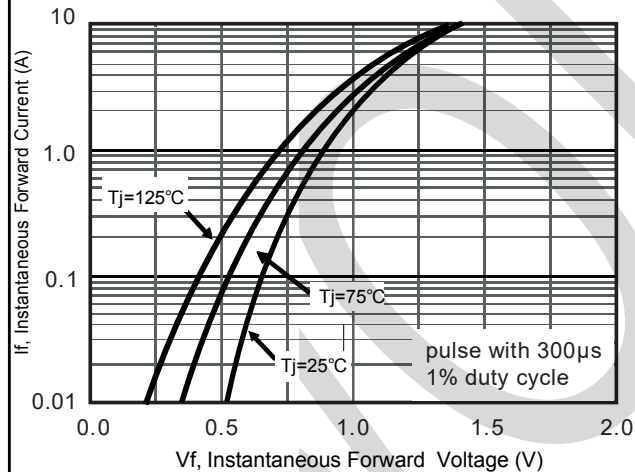
RATINGS AND CHARACTERISTICS CURVES (TA = 25 °C unless otherwise noted)



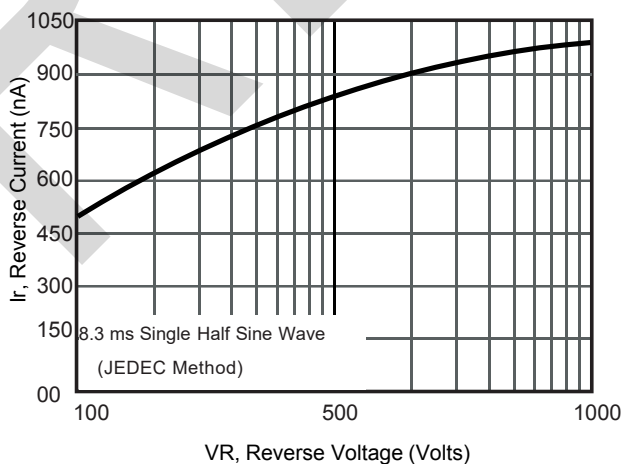
Current Derating, Case



Typical Junction Capacitance

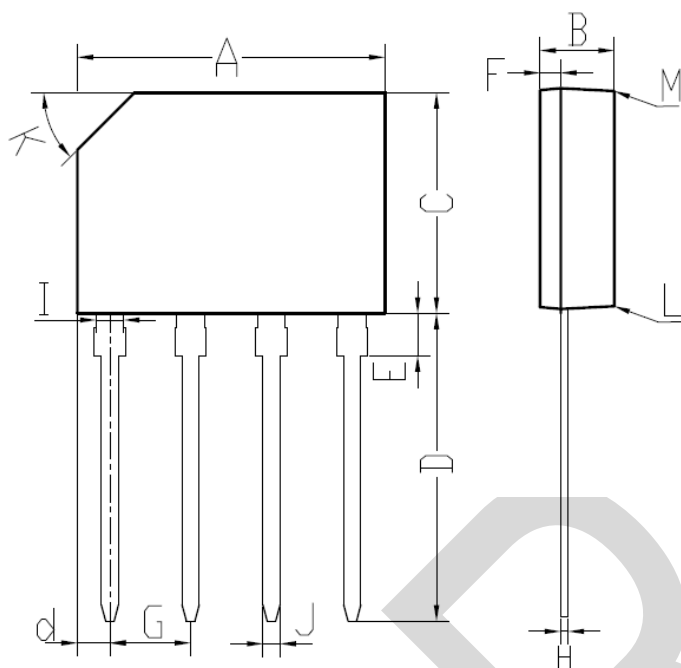


Typical Forward Voltage



Typical Reverse Current

PACKAGE OUTLINE DIMENSIONS



GBP		
DIM.	MIN.	MAX.
A	14.20	14.70
B	3.30	3.60
C	10.20	10.60
D	13.80	14.40
d	1.40	1.70
E	1.80	2.20
F	0.80	1.10
G	3.71	3.91
H	0.30	0.55
I	1.22	1.42
J	0.76	0.86
K	2.7 x 45° (Typ)	
L	#	3°
M	#	2°
All Dimensions in millimeter		